

ZXMP3A16N8

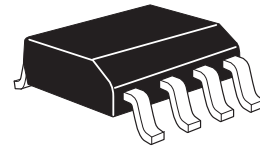
30V P-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY

$V_{(BR)DSS} = -30V$; $R_{DS(ON)} = 0.040\Omega$; $I_D = -6.7A$

DESCRIPTION

This new generation of trench MOSFETs from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



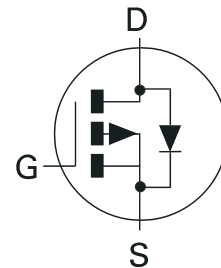
SO8

FEATURES

- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- Low profile SOIC package

APPLICATIONS

- Disconnect switches
- Motor control



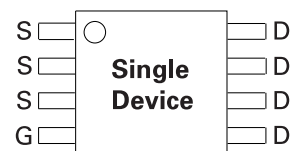
ORDERING INFORMATION

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXMP3A16N8TA	7"	12mm	500 units
ZXMP3A16N8TC	13"	12mm	2500 units

DEVICE MARKING

- ZXMP
3A16

PINOUT



Top View

ZXMP3A16N8

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DSS}	-30	V
Gate Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $V_{GS}=-10V$; $T_A=25^{\circ}C$ (b) $V_{GS}=-10V$; $T_A=70^{\circ}C$ (b) $V_{GS}=-10V$; $T_A=25^{\circ}C$ (a)	I_D	-6.7 -5.4 -5.6	A
Pulsed Drain Current (c)	I_{DM}	-26	A
Continuous Source Current (Body Diode) (b)	I_S	-3.2	A
Pulsed Source Current (Body Diode) (c)	I_{SM}	-26	A
Power Dissipation at $T_A=25^{\circ}C$ (a) Linear Derating Factor	P_D	1.9 15.2	W mW/ $^{\circ}C$
Power Dissipation at $T_A=25^{\circ}C$ (b) Linear Derating Factor	P_D	2.8 22.4	W mW/ $^{\circ}C$
Operating and Storage Temperature Range	$T_j:T_{stg}$	-55 to +150	$^{\circ}C$

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{\theta JA}$	65	$^{\circ}C/W$
Junction to Ambient (b)	$R_{\theta JA}$	45	$^{\circ}C/W$

NOTES

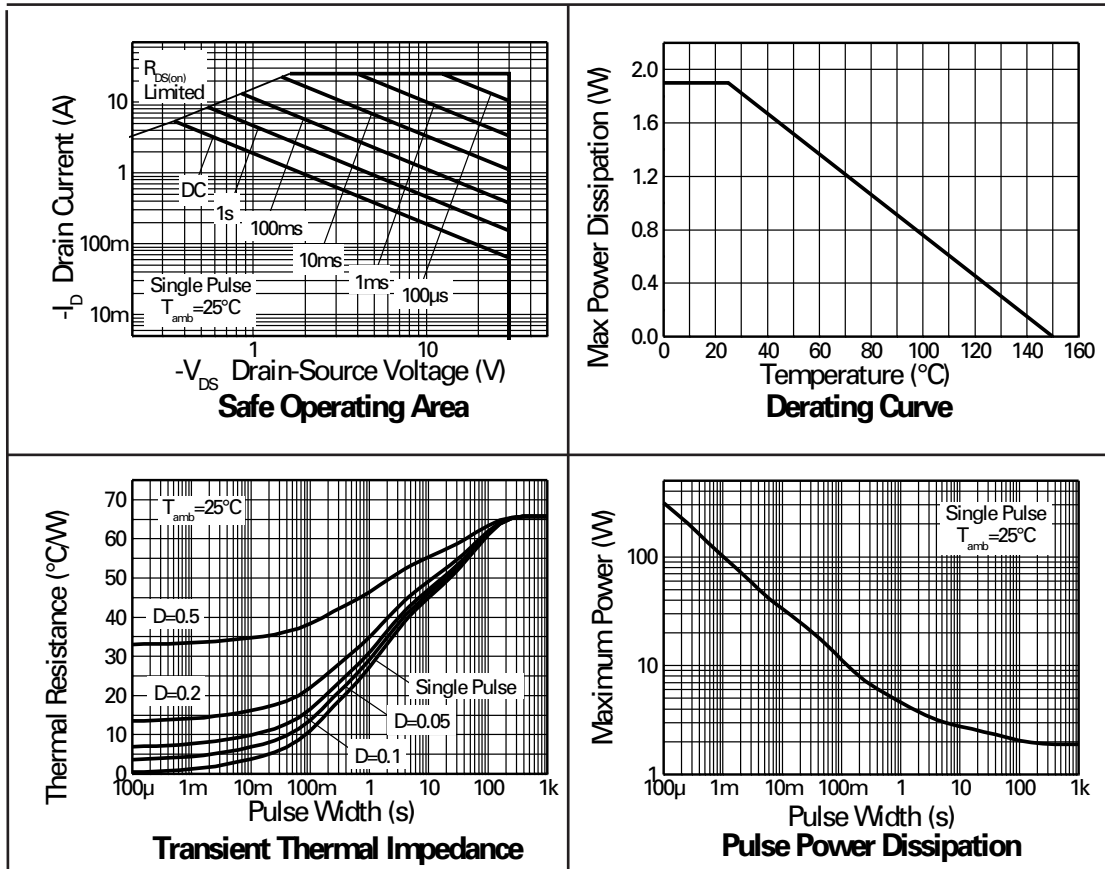
(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

(b) For a device surface mounted on FR4 PCB measured at $t \leq 5$ secs.

(c) Repetitive rating 25mm x 25mm FR4 PCB, $D = 0.05$, pulse width 10 μs - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.

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CHARACTERISTICS



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ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

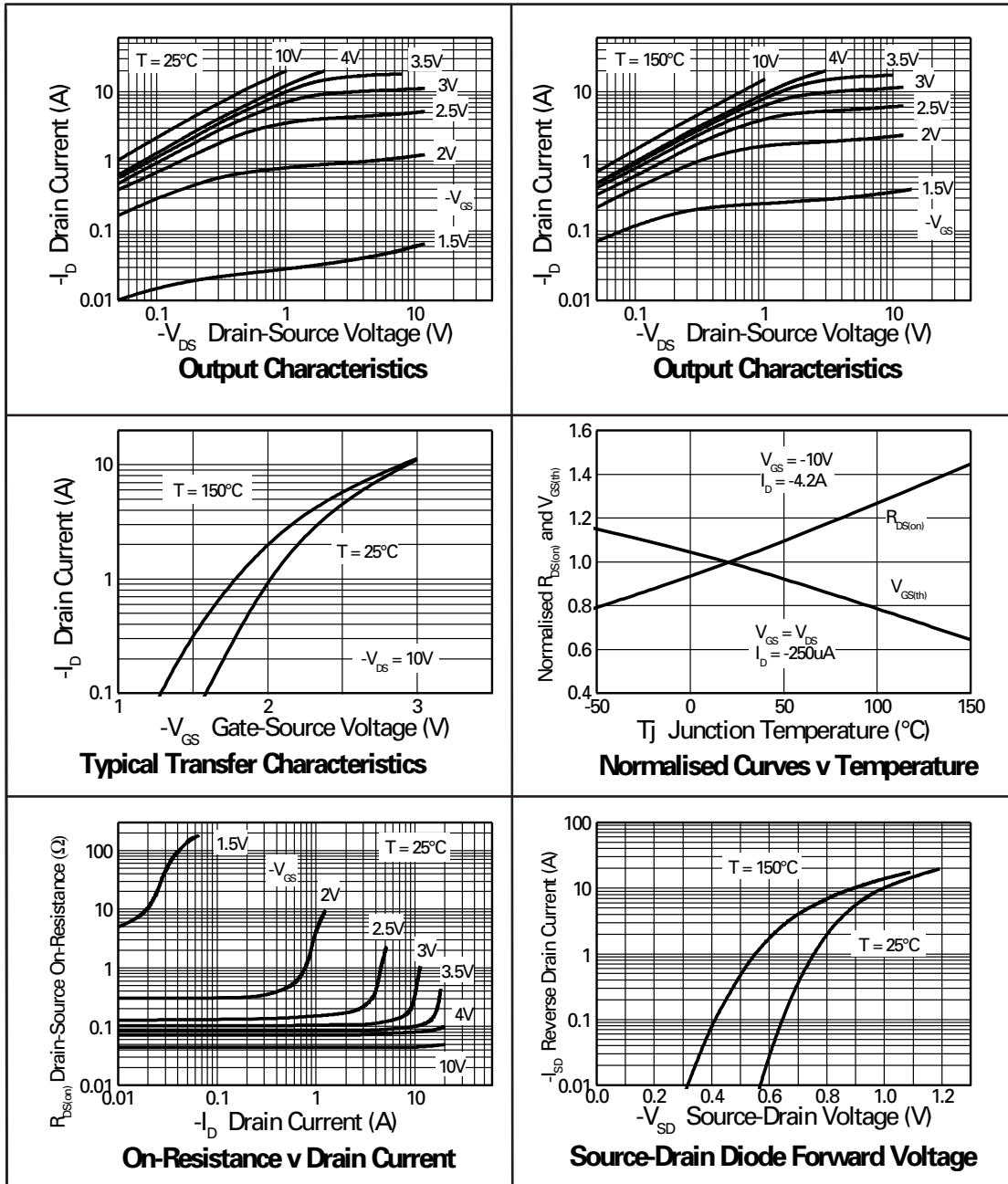
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	-30			V	I _D =-250μA, V _{GS} =0V
Zero Gate Voltage Drain Current	I _{DSS}			-1.0	μA	V _{DS} =-30V, V _{GS} =0V
Gate-Body Leakage	I _{GSS}			100	nA	V _{GS} =±20V, V _{DS} =0V
Gate-Source Threshold Voltage	V _{GS(th)}	-1.0			V	I _D =-250μA, V _{DS} = V _{GS}
Static Drain-Source On-State Resistance (1)	R _{DS(on)}			0.040 0.070	Ω Ω	V _{GS} =-10V, I _D =-4.2A V _{GS} =-4.5V, I _D =-3.4A
Forward Transconductance (1)(3)	g _{fs}		9.2		S	V _{DS} =-15V, I _D =-4.2A
DYNAMIC (3)						
Input Capacitance	C _{iss}		1022		pF	V _{DS} =-15 V, V _{GS} =0V, f=1MHz
Output Capacitance	C _{oss}		267		pF	
Reverse Transfer Capacitance	C _{rss}		229		pF	
SWITCHING(2) (3)						
Turn-On Delay Time	t _{d(on)}		3.8		ns	V _{DD} =-15V, I _D =-1A R _G =6.0Ω, V _{GS} =-10V
Rise Time	t _r		6.5		ns	
Turn-Off Delay Time	t _{d(off)}		37.1		ns	
Fall Time	t _f		21.4		ns	
Gate Charge	Q _g		17.2		nC	V _{DS} =-15V, V _{GS} =-5V, I _D =-4.2A
Total Gate Charge	Q _g		29.6		nC	V _{DS} =-15V, V _{GS} =-10V, I _D =-4.2A
Gate-Source Charge	Q _{gs}		2.8		nC	
Gate-Drain Charge	Q _{gd}		8.6		nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage (1)	V _{SD}		-0.85	-0.95	V	T _J =25°C, I _S =-3.6A, V _{GS} =0V
Reverse Recovery Time (3)	t _{rr}		21.7		ns	T _J =25°C, I _F =-2A, di/dt= 100A/μs
Reverse Recovery Charge (3)	Q _{rr}		16.1		nC	

NOTES

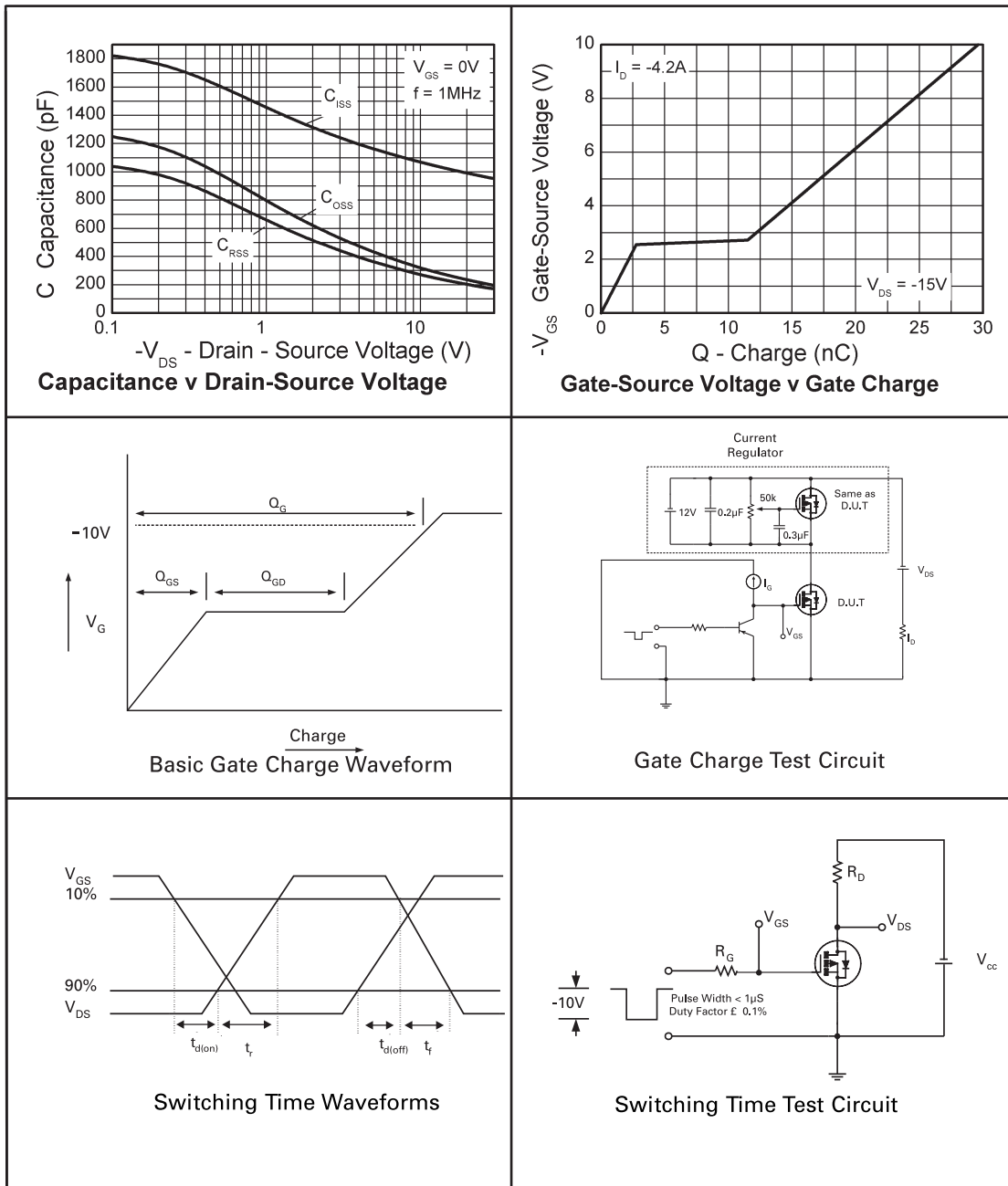
- (1) Measured under pulsed conditions. Width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.
 (2) Switching characteristics are independent of operating junction temperature.
 (3) For design aid only, not subject to production testing.

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CHARACTERISTICS



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"Last time buy (LTB)"Device will be discontinued and last time buy period and delivery is in effect

"Not recommended for new designs"Device is still in production to support existing designs and production

"Obsolete"Production has been discontinued

Datasheet status key:

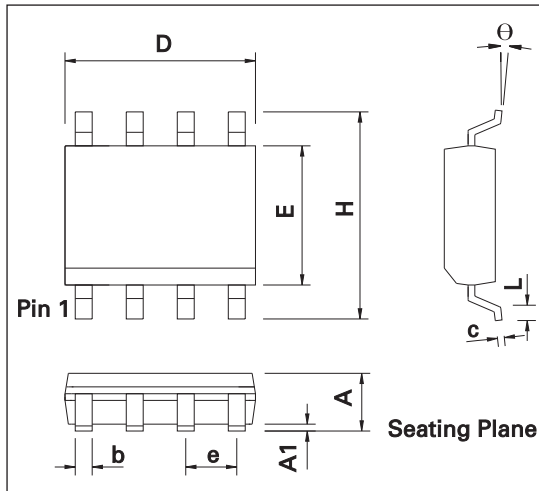
"Draft version" This term denotes a very early datasheet version and contains highly provisional information, which may change in any manner without notice.

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PACKAGE OUTLINE



CONTROLLING DIMENSIONS ARE IN INCHES
APPROX IN MILLIMETERS

PACKAGE DIMENSIONS

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
A	1.35	1.75	0.053	0.069	e	1.27 BSC		0.050 BSC	
A1	0.10	0.25	0.004	0.010	b	0.33	0.51	0.013	0.020
D	4.80	5.00	0.189	0.197	c	0.19	0.25	0.008	0.010
H	5.80	6.20	0.228	0.244	Θ	0°	8°	0°	8°
E	3.80	4.00	0.150	0.157	h	0.25	0.50	0.010	0.020
L	0.40	1.27	0.016	0.050	-	-	-	-	-

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